

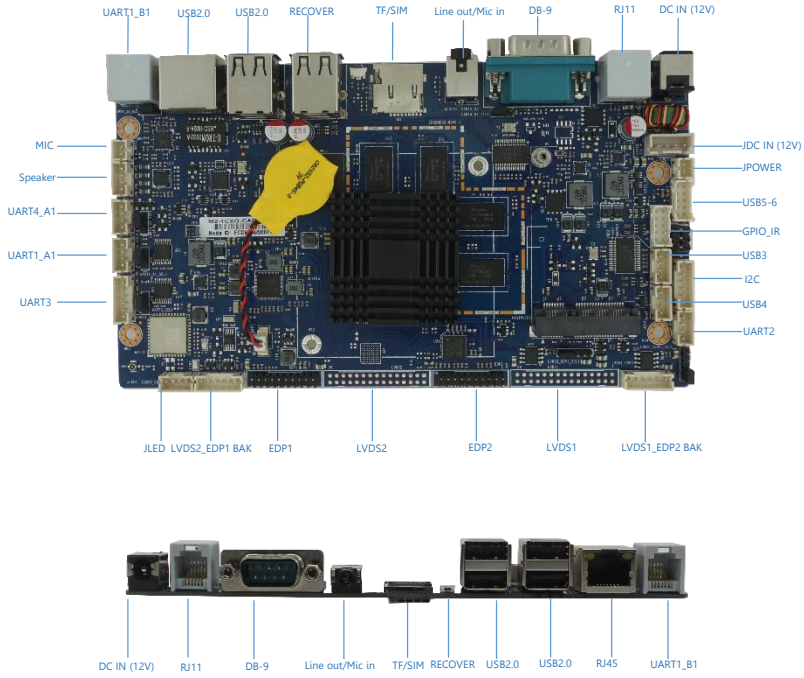


- RK3288W 4Core SOC , ARM Cortex-A17, Max. 1.6GHz
- Onboard 2GB DDR3L (optional 1GB )
- Supports dual display of LVDS1/LVDS2/EDP1/EDP2(option )
- Onboard 8GB EMMC (optional 16/32GB)
- 802.11b/g/n WIFI+BT
- 8 USB2.0 , 3 COM
- 10/100M Etherne
- Supports GPIO/I2C/IR/RJ11/4G/Watchdog
- Supports 12V DC Input

## Specification

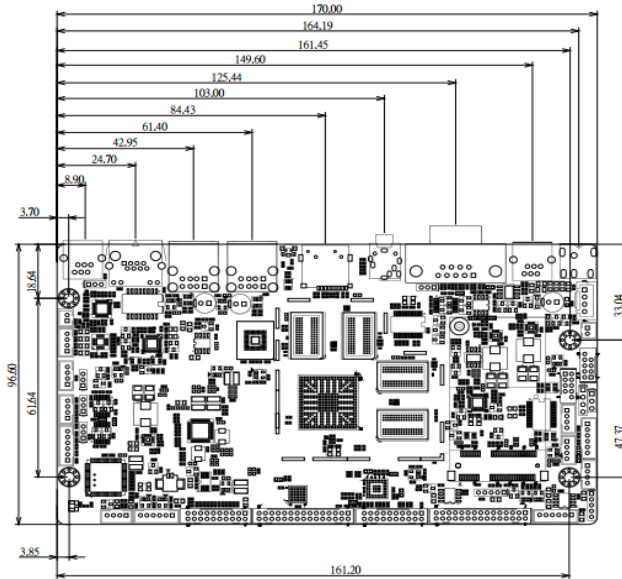
<b>CPU</b>	RK3288W 4Core SOC , ARM Cortex-A17, Max. 1.6GHz
<b>GPU</b>	Mali-T764
<b>Memory</b>	1GB/2GB DDR3L optional
<b>OS</b>	Android 7.1
<b>Storage</b>	Onboard 8GB EMMC (optional 16/32GB)
<b>Audio</b>	I2S Audio IC , ALC5651
<b>LAN</b>	1 x 10/100Mbps , RTL8201F
<b>Displays</b>	2 ,30 Pin, 2 x 15PIN LVDS Port 2 ,20 Pin, 2 x 10PIN eDP Port 1 x 6pin LVDS1_EDP2 BAK 1 x 6pin LVDS2_EDP1 BAK
<b>Audio interfaces</b>	1 x 3.5mm Audio jack : Line out 1 x Mic in 2pin wafer Amplifier : 3W/4Ω x 2
<b>USB</b>	IO: 4 USB2.0 Internal : 4 x USB2.0
<b>Serial</b>	5 x COM ( 1个DB-9可选RS232/TTL/RS485,默认RS232 , 3个COM 4pin , RS232可选RS232/TTL , 默认RS232(UART1_A1,UART3,UART4_A1), 1个RJ11- 6pin ) DB-9 (丝印:UART4_B1)与(UART4_A1)Co-lay RJ11-6PIN (丝印:UART1_B1) 与UART1_A1 Co-lay Support 5/12V optional
<b>Expansion</b>	1 x Mini PCIe for 3G/4G mobile network module 1 x SIM Slot,1 x TF Slot,1 x IR header 1 x TP-I2C(1*6pin 2.0mm wafer) 4 x GPIO header,1x JDC IN header 1x JPOWER header,1 x JLED header
<b>Power</b>	12V DC input
<b>SIZE</b>	170mm x 96mm
<b>Working temperture</b>	-5~50°C
<b>Working Humidity</b>	10%~90% non-condensing
<b>Storage temperture</b>	-20~70°C
<b>Non working Humidity</b>	5%~90% non-condensing

## View



## Size

## IO



## Information

P/N	Description
R28P-216LE	RK3288W/LVDS1/EDP1/8 USB2.0/3 COM/ 1 LAN
R28P-216EE	RK3288W/LVDS1/LVDS2/8 USB2.0/3 COM/ 1 LAN
R28P-216LL	RK3288W/LVDS1/LVDS2/8 USB2.0/3 COM/ 1 LAN

Product descriptions are subject to change without notice.